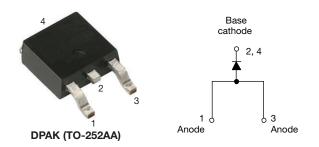


# High Voltage Surface Mount Input Rectifier Diode, 8 A



PRIMARY CHARACTERISTICS					
I <sub>F(AV)</sub>	8 A				
$V_{R}$	1600 V				
V <sub>F</sub> at I <sub>F</sub>	1.1 V				
I <sub>FSM</sub>	150 A				
T <sub>J</sub> max.	150 °C				
Package	DPAK (TO-252AA)				
Circuit configuration	Single				

#### **FEATURES**

- · Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C







FREE

### **APPLICATIONS**

- · Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

#### **DESCRIPTION**

The VS-8EWS16S-M3 rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The **high reverse voltage** range available allows design of input stage primary rectification with **outstanding voltage surge** capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS							
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS				
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 μm) copper	1.2	1.6	٨				
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	А				
Aluminum IMS with heatsink, R <sub>thCA</sub> = 5 °C/W	5.5	6.5					

#### Note

• T<sub>A</sub> = 55 °C, T<sub>J</sub> = 125 °C, footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL CHARACTERISTICS VALUES UN						
I <sub>F(AV)</sub>	Sinusoidal waveform	8	A			
V <sub>RRM</sub>		1600	V			
I <sub>FSM</sub>		150	A			
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V			
T <sub>J</sub>		-40 to +150	°C			

VOLTAGE RATINGS			
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE	I <sub>RRM</sub> AT 150 °C
	V	V	mA
VS-8EWS16S-M3	1600	1700	0.5

### VS-8EWS16S-M3 Series

# Vishay Semiconductors

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum average forward current	I <sub>F(AV)</sub>	$T_C$ = 105 °C, 180° conduction half sine wave	8		
Maximum peak one cycle		10 ms sine pulse, rated V <sub>RRM</sub> applied	125	Α	
non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, no voltage reapplied	150		
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s	
Maximum i-t for fusing	1-1	10 ms sine pulse, no voltage reapplied 110		A-5	
Maximum I <sup>2</sup> √t for fusing	l <sup>2</sup> √t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A <sup>2</sup> √s	

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS
Maximum forward voltage drop	V <sub>FM</sub>	8 A, T <sub>J</sub> = 25 °C		1.1	V
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C		20	mΩ
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C		0.82	V
Maximum roverse leakage current		T <sub>J</sub> = 25 °C	V <sub>B</sub> = Rated V <sub>BBM</sub>	0.05	mA
Maximum reverse leakage current	IRM	T <sub>J</sub> = 150 °C	v <sub>R</sub> = nateu v <sub>RRM</sub>	0.50	IIIA

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-40 to +150	°C	
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W	
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA</sub> <sup>(1)</sup>		62	C/VV	
Approximate weight			1	g	
Approximate weight			0.03	oz.	
Marking device		Case style DPAK (TO-252AA)	8EW	S16S	

#### Note

<sup>(1)</sup> When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994

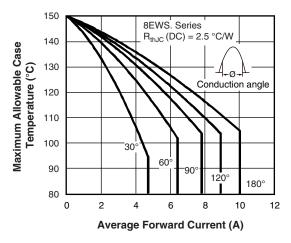


Fig. 1 - Current Rating Characteristics

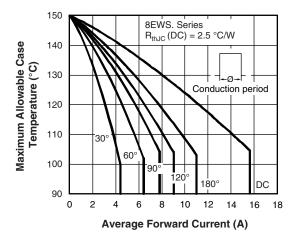


Fig. 2 - Current Rating Characteristics

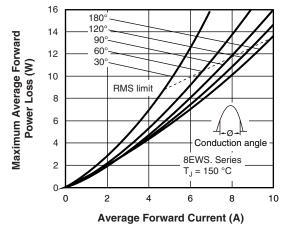


Fig. 3 - Forward Power Loss Characteristics

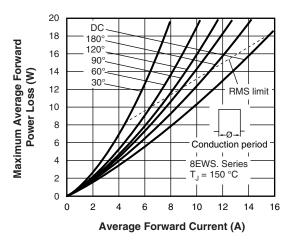


Fig. 4 - Forward Power Loss Characteristics

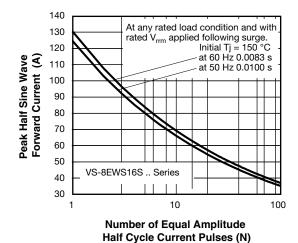


Fig. 5 - Maximum Non-Repetitive Surge Current

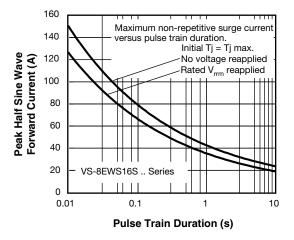


Fig. 6 - Maximum Non-Repetitive Surge Current

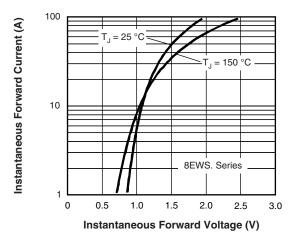


Fig. 7 - Forward Voltage Drop Characteristics

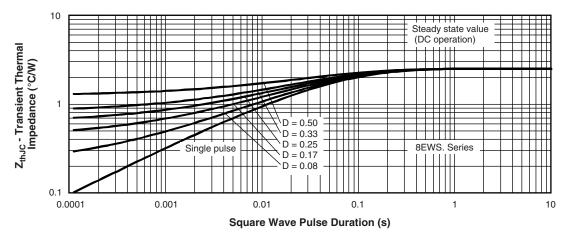
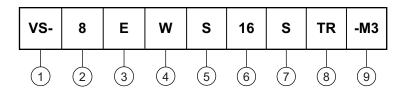


Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristics

### **ORDERING INFORMATION TABLE**

**Device code** 



Vishay Semiconductors product

Current rating (8 = 8 A)

Circuit configuration: E = single diode

Package:

W = D-PAK

5 Type of silicon:

S = standard recovery rectifier

Voltage code x 100 = V<sub>RRM</sub> (16 = 1600 V)

S = surface mountable

• TR = tape and reel

• TRR = tape and reel (right oriented)

• TRL = tape and reel (left oriented)

9 Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

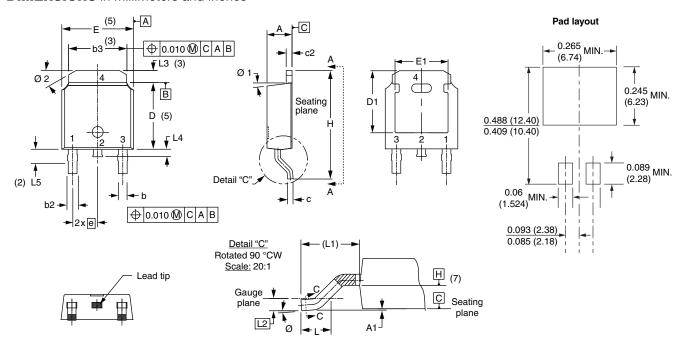
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-8EWS16S-M3	75	3000	Antistatic plastic tubes			
VS-8EWS16STR-M3	2000	2000	13" diameter reel			
VS-8EWS16STRL-M3	3000	3000	13" diameter reel			
VS-8EWS16STRR-M3	3000	3000	13" diameter reel			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95627			
Part marking information	www.vishay.com/doc?95176			
Packaging information	www.vishay.com/doc?95033			
SPICE model	www.vishay.com/doc?96960			



# D-PAK (TO-252AA) "M"

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	1	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108	REF.	
L2	0.51	BSC	0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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